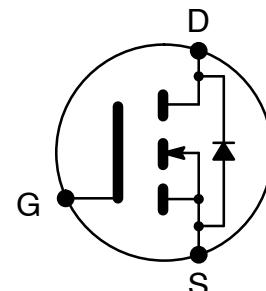




**NTE2904**  
**MOSFET**  
**N-Ch, Enhancement Mode**  
**High Speed Switch**  
**TO-220 Type Package**

**Features:**

- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- +175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated



**Absolute Maximum Ratings:**

Continuous Drain Current ( $V_{GS} = 10V$ ), $I_D$	
$T_C = +25^\circ C$ .....	64A
$T_C = +100^\circ C$ .....	45A
Pulsed Drain Current (Note 1), $I_{DM}$ .....	210A
Power Dissipation ( $T_C = +25^\circ C$ ), $P_D$ .....	7130W
Derate Linearly Above 25°C .....	0.83W/°C
Gate-to-Source Voltage, $V_{GS}$ .....	±20V
Avalanche Current (Note 1), $I_{AR}$ .....	32A
Repetitive Avalanche Energy (Note 1), $E_{AR}$ .....	13mJ
Peak Diode Recovery dv/dt (Note 3), dv/dt .....	5.0V/ns
Operating Junction Temperature Range, $T_J$ .....	-55° to +175°C
Storage Temperature Range, $T_{stg}$ .....	-55° to +175°C
Lead Temperature (During Soldering, 1.6mm from case for 10sec), $T_L$ .....	+300°C
Mounting Torque (6-32 or M3 Screw) .....	10 lbf•in (1.1N•m)
Thermal Resistance, Junction-to-Case, $R_{thJC}$ .....	1.15°C/W
Thermal Resistance, Junction-to-Ambient, $R_{thJA}$ .....	62°C/W
Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface), $R_{thCS}$ .....	0.5°C/W

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 2. Starting  $T_J = +25^\circ C$ ,  $L = 0.37mH$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 32A$

Note 3.  $I_{SD} \leq 32A$ ,  $di/dt \leq 220A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq +175^\circ C$

## Electrical Characteristics: ( $T_J = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	55	—	—	V
Breakdown Voltage Temp. Coefficient	$\frac{\Delta V_{(\text{BR})\text{DSS}}}{\Delta T_J}$	Reference to $+25^\circ\text{C}$ , $I_D = 1\text{mA}$	—	0.058	—	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 32\text{A}$ , Note 4	—	—	0.014	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	—	4.0	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 25\text{V}, I_D = 32\text{A}$ , Note 4	24	—	—	mhos
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 55\text{V}, V_{\text{GS}} = 0\text{V}$	—	—	25	$\mu\text{A}$
		$V_{\text{DS}} = 44\text{V}, V_{\text{GS}} = 0\text{V}, T_J = +150^\circ\text{C}$	—	—	250	$\mu\text{A}$
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = 20\text{V}$	—	—	100	nA
Gate-to-Source Reverse Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = -20\text{V}$	—	—	-100	nA
Total Gate Charge	$Q_g$	$I_D = 32\text{A}, V_{\text{DS}} = 44\text{V}, V_{\text{GS}} = 10\text{V}$	—	—	81	nC
Gate-to-Source Charge	$Q_{\text{gs}}$		—	—	19	nC
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		—	—	30	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 28\text{V}, I_D = 32\text{A}, R_G = 0.85\Omega$ , $R_D = 79\text{ }\Omega$ , Note 4	—	12	—	ns
Rise Time	$t_r$		—	78	—	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		—	34	—	ns
Fall Time	$t_f$		—	50	—	ns
Internal Drain Inductance	$L_D$	Between lead, .250in. (6.0) mm from package and center of die contact	—	4.5	—	nH
Internal Source Inductance	$L_S$		—	7.5	—	nH
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	—	1970	—	pF
Output Capacitance	$C_{\text{oss}}$		—	470	—	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		—	120	—	pF
Single Pulse Avalanche Energy	$E_{\text{AS}}$	$I_{\text{AS}} = 32\text{A}, L = 0.37\text{mH}$ , Note 2	—	700 Note 5	190 Note 6	mJ

## Source-Drain Ratings and Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	$I_S$		—	—	64	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$	Note 1	—	—	210	A
Diode Forward Voltage	$V_{\text{SD}}$	$T_J = +25^\circ\text{C}, I_S = 32\text{A}, V_{\text{GS}} = 0\text{V}$ , Note 4	—	—	1.3	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +25^\circ\text{C}, I_F = 32\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ , Note 4	—	68	100	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		—	220	330	$\mu\text{C}$
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is neglegible (turn-on is dominated by $L_S+L_D$ )				

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 4. Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

Note 5. This is the destructive value not limited to the thermal limit.

Note 6. This is the thermal limited value.

